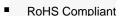


April 2013

FDZ8040L Integrated Load Switch

Features

- Optimized for Low-Voltage Core ICs in Portable Systems
- Very Small Package Dimension: WLCSP 0.8 X 0.8 X 0.5 mm³
- Current = 1.2 A, V_{IN} Max. = 4 V
- Current = 2 A, V_{IN} Max. = 4 V (Pulsed)
- $R_{DS(on)} = 80 \text{ m}\Omega \text{ at } V_{ON} = V_{IN} = 4 \text{ V}$
- $R_{DS(on)} = 85 \text{ m}\Omega \text{ at } V_{ON} = V_{IN} = 3.6 \text{ V}$
- $R_{DS(on)} = 90 \text{ m}\Omega \text{ at } V_{ON} = V_{IN} = 3 \text{ V}$
- $R_{DS(on)} = 360 \text{ m}\Omega \text{ at } V_{ON} = V_{IN} = 0.9 \text{ V}$
- R_{DS(on)} = 1000 mΩ at $V_{ON} = V_{IN} = 0.8 \text{ V}$





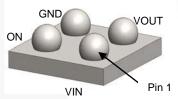


Figure 1. Bottom View

Description

This device is particularly suited for compact power management in portable applications needing 0.8 V to 4 V input and 1.2 A output current capability. This load switch integrated a level-shifting function that drives a P-channel power MOSFET in a very small 0.8 X 0.8 X 0.5 mm³ WLCSP package.

Applications

- Load Switch
- Power Management in Portable Applications



Figure 2. Top View

Ordering Information

Part Number	Device Mark	Ball Pitch	Operating Temperature Range	Switch	Package	Packing Method
FDZ8040L	ZM	0.4 mm	-40 to 85°C	80 mΩ, P-Channel MOSFET	0.8 x 0.8 x 0.5 mm ³ WLCSP	Tape & Reel

Typical Application

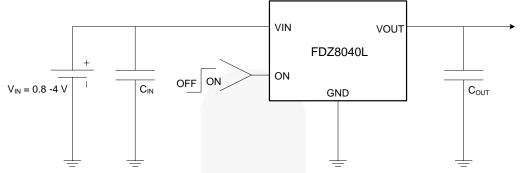


Figure 3. Typical Application

Block Diagram

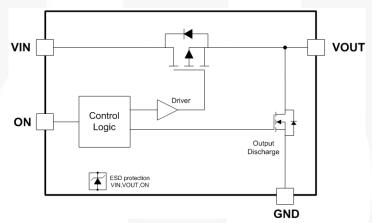


Figure 4. Internal Block Diagram

Pin Configuration

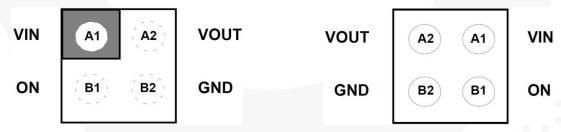


Figure 5. Top View (Bumps Down) Figure 6. Bottom View (Bumps Up)

Pin Descriptions

Pin#	Name	Description	
A1	VIN	pply Input: Input to the load switch	
A2	VOUT	witch Output: Output of the load switch	
B1	ON	DN/OFF Control Input	
B2	GND	round	

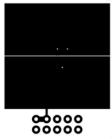
Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

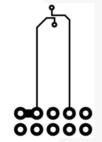
Symbol	Parameter			Max.	Unit
V _{IN}	Voltage on VIN, VOUT, ON to GND			4.2	V
I _{OUT_C}	I _{OUT} -Load Current (Continuous) ^(1a)			1.2	Α
I _{OUT_P}	I _{OUT} -Load Current (Pulsed)			2	Α
P _D	Power Dissipation at T _A = 25°C ^(1a)			0.9	W
T _A	Operating Temperature Range		-40	85	°C
T _{STG}	Storage Temperature		-65	150	°C
R⊝ _{JA}	Thermal Resistance, Junction to Ar	mbient ^(1a)		135	°C/W
ESD	Electrostatic Discharge Canability	Human Body Model, JESD22-A114	8		kV
	Electrostatic Discharge Capability Charged Device Model, JESD22-C101		2		KV

Notes:

RO_{JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal
reference is defined as the solder mounting surface of the drain pins. RO_{JC} is guaranteed by design, while RO_{JA}
is determined by the board design.



a. 135°C/W when mounted on a1-inch square pad of 2-oz copper.



b. 360°C/W when mounted on a minimum pad of 2-oz copper.

2. Pulse test: pulse width < 300 μs; duty cycle < 2.0%.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Pa	Min.	Max.	Unit	
V _{IN}	Voltage on VIN Pin	0.8	4.0	V	
V_{ON}	Voltage on ON Pin	0.7	4.0	V	
т	Operating Temperature	1 V to 4 V	-40	85	°C
T_A	Range 0.8 V to 4 V		-10	65	

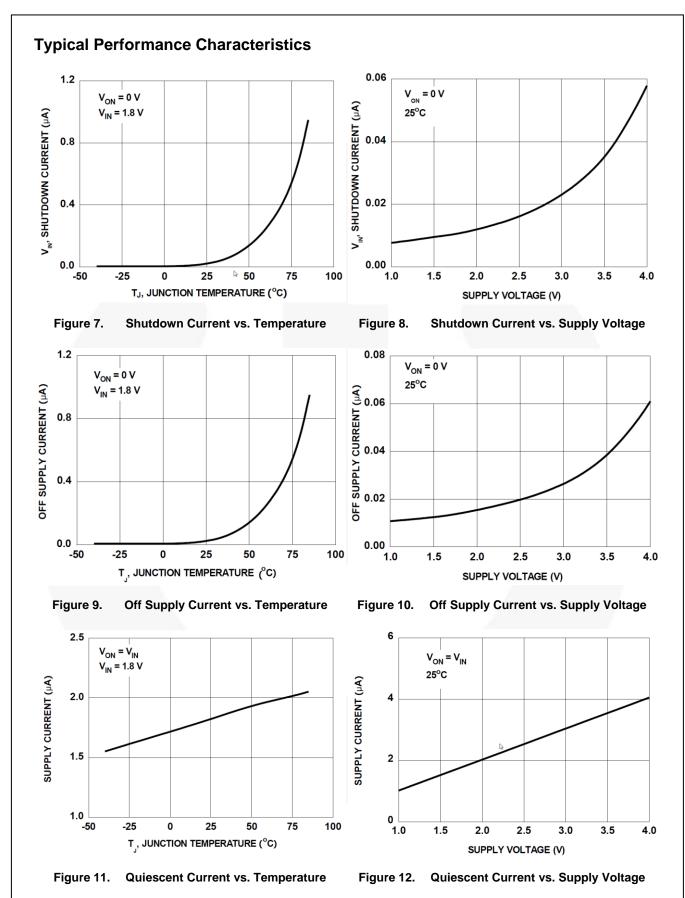
Electrical Characteristics

 T_{J} = 25°C and $V_{IN}\!\!=\!\!1.8$ V, unless otherwise noted.

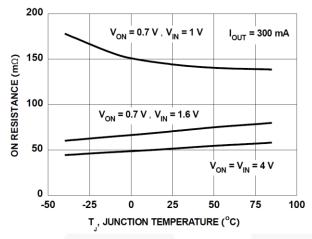
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	
V_{IN}	Operation Voltage		0.8		4.0	V	
\/	ON legat Legis Legy Voltage	1.6 V ≤ V _{IN} ≤ 4.0 V			0.35	V	
V_{IL}	ON Input Logic Low Voltage	$0.8 \text{ V} \le \text{V}_{\text{IN}} \le 1.6 \text{ V}$			0.25	V	
\/	ON Input Logic High Voltage	$1.6 \text{ V} \le \text{V}_{\text{IN}} \le 4.0 \text{ V}$	1.0			.,	
V_{IH}	ON Input Logic High Voltage	$0.8 \text{ V} \le \text{V}_{\text{IN}} \le 1.6 \text{ V}$	0.7			V	
I_Q	Quiescent Current	$I_{OUT} = 0 \text{ mA}, V_{IN} = V_{ON} = 1.8 \text{ V}$			2.1	μA	
$I_{Q(off)}$	Off Supply Current	$I_{OUT} = 0$ mA, $V_{IN} = 1.8$ V, $V_{ON} = GND$			1	μA	
I _{SD(off)}	Off Switch Current	$V_{ON} = GND$, $V_{OUT} = 0$ V, $V_{IN} = 1.8$ V			100	nA	
I _{ON}	ON Input Leakage	$V_{ON} = V_{IN}$ or GND			1	μA	
R_{PD}	Output Discharge Pull-Down Resistance			200		Ω	
- 2		V _{ON} = V _{IN} = 4 V, I _{OUT} = 300 mA		50	80		
		$V_{ON} = V_{IN} = 3.6 \text{ V}, I_{OUT} = 300 \text{ mA}$		51	85		
		$V_{ON} = V_{IN} = 3 \text{ V}, I_{OUT} = 300 \text{ mA}$		54	90		
		$V_{ON} = 0.7 \text{ V}, V_{IN} = 1.6 \text{ V}, I_{OUT} = 300 \text{ mA}$		73	110		
		$V_{ON} = 0.7 \text{ V}, V_{IN} = 1 \text{ V}, I_{OUT} = 300 \text{ mA}$		140	309		
R _{DS(ON)}	Static Drain-Source	$V_{ON} = V_{IN} = 0.9 \text{ V}, I_{OUT} = 10 \text{ mA}$		186	360	mΩ	
-(- /	On-Resistance	$V_{ON} = V_{IN} = 0.8 \text{ V}, I_{OUT} = 10 \text{ mA}$		348	1000		
		$V_{ON} = V_{IN} = 0.9 \text{ V}, I_{OUT} = 10 \text{ mA}, \\ T_J = 10 \sim 85^{\circ}\text{C}$		194	370		
		$V_{ON} = V_{IN} = 0.8 \text{ V}, I_{OUT} = 10 \text{ mA},$ $T_J = 10 \sim 85^{\circ}\text{C}$		268	750		
		$V_{IN} = 3.6 \text{ V}, I_{OUT} = 300 \text{ mA}, T_J = 85^{\circ}\text{C}$		59	102		

Switching Characteristics

Symbol	Parameter	Test Conditions	Typical	Unit
td(on)	Turn-On Delay Time		22	μs
t _r	Turn-On Rise Time	V 40VV 07V 0 4VF D 5000	23	μs
td(off)	Turn-Off Delay Time	$V_{IN} = 1.6 \text{ V}, V_{ON} = 0.7 \text{ V}, C_L = 1 \mu\text{F}, R_L = 500 \Omega$	109	μs
tf	Turn-Off Fall Time		285	μs
td(on)	Turn-On Delay Time		37	μs
tŗ	Turn-On Rise Time	V 4VV 40V 0 4 5 B 500 0	35	μs
td(off)	Turn-Off Delay Time	$V_{IN} = 1 \text{ V}, V_{ON} = 1.8 \text{ V}, C_L = 1 \mu\text{F}, R_L = 500 \Omega$	112	μs
tf	Turn-Off Fall Time		332	μs
t _{d(on)}	Turn-On Delay Time		20	μs
t _r	Turn-On Rise Time		22	μs
td(off)	Turn-Off Delay Time	$V_{IN} = 1.8 \text{ V}, V_{ON} = 1.8 \text{ V}, C_L = 1 \mu\text{F}, R_L = 500 \Omega$	122	μs
tf	Turn-Off Fall Time		296	μs
td(on)	Turn-On Delay Time		15	μs
tr	Turn-On Rise Time	T.,,,	19	μs
td(off)	Turn-Off Delay Time	$V_{IN} = 2.5 \text{ V}, V_{ON} = 1.8 \text{ V}, C_L = 1 \mu\text{F}, R_L = 500 \Omega$	160	μs
tf	Turn-Off Fall Time		295	μs
td(on)	Turn-On Delay Time		13	μs
t _r	Turn-On Rise Time		18	μs
td(off)	Turn-Off Delay Time	$V_{IN} = 3.3 \text{ V}, V_{ON} = 1.8 \text{ V}, C_L = 1 \mu\text{F}, R_L = 500 \Omega$	193	μs
tf	Turn-Off Fall Time		305	μs
td(on)	Turn-On Delay Time		53	μs
t _r	Turn-On Rise Time	,	56	μs
td(off)	Turn-Off Delay Time	$V_{IN} = 0.8 \text{ V}, V_{ON} = 0.8 \text{ V}, C_L = 1 \mu\text{F}, R_L = 500 \Omega$	143	μs
tf	Turn-Off Fall Time		532	μs
td(on)	Turn-On Delay Time		51	μs
t _r	Turn-On Rise Time		54	μs
td(off)	Turn-Off Delay Time	$V_{IN} = 0.9 \text{ V}, V_{ON} = 0.9 \text{ V}, C_L = 1 \mu\text{F}, R_L = 500 \Omega$	148	μs
t _f	Turn-Off Fall Time		525	μs



Typical Performance Characteristics



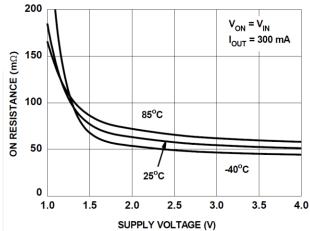


Figure 13. R_{ON} vs. Temperature

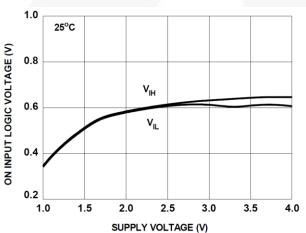


Figure 14. Ron vs. Supply Voltage

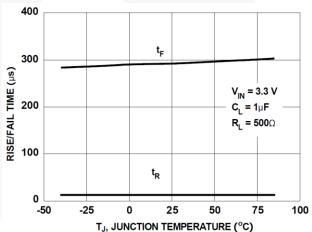


Figure 15. ON-Pin Threshold vs. VIN

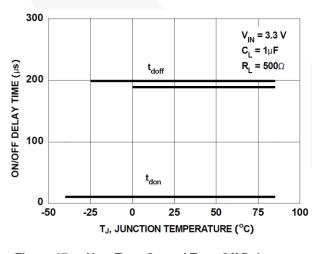


Figure 16. V_{OUT} Rise and Fall Time vs. Temperature at R_L =500 Ω

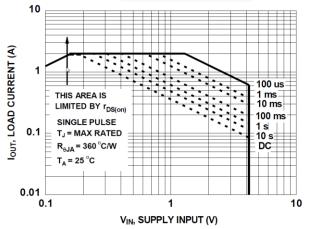


Figure 17. V_{OUT} Turn-On and Turn-Off Delay vs. Temperature at R_L =500 Ω

Figure 18. Forward Bias Safe Operation Area



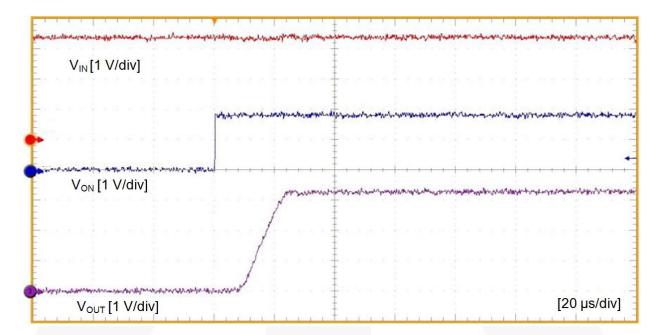


Figure 19. Turn-On Response ($V_{IN} = 3.3 \text{ V}$, $C_{OUT}=1 \mu\text{F}$, $R_L=500 \Omega$)

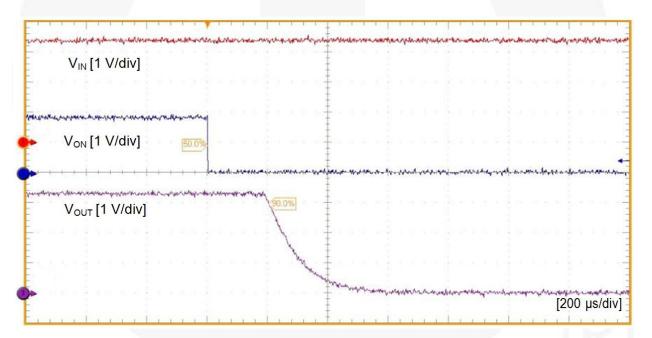


Figure 20. Turn-Off Response (V_{IN} = 3.3 V, C_{OUT} =1 μ F, R_L =500 Ω)

Functional Description

The FDZ8040L is a low- $R_{DS(ON)}$ P-channel load switch packaged in space-saving 0.8 x 0.8 WLCSP.

The core of the device is an $80 \text{ m}\Omega$ P-channel MOSFET capable of functioning over a wide input operating range

of 0.8-4 V. The ON pin, an active HIGH TTL-compatible input that supports input as low as 0.7 V, controls the state of the switch.

Applications Information

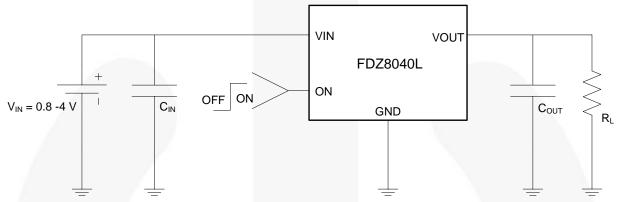


Figure 21. Typical Application

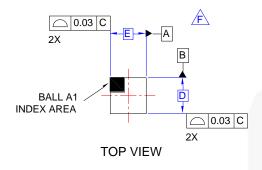
Input Capacitor

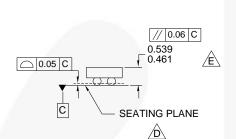
To reduce device inrush current effect, a 0.1 μ F ceramic capacitor, C_{IN} , is recommended close to the VIN pin. A higher value of C_{IN} can be used to further reduce the voltage drop experienced as the switch is turned on into a large capacitive load.

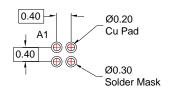
Output Capacitor

FDZ8040L works without an output capacitor. However, if parasitic board inductance forces V_{OUT} below GND when switching off, a 0.1 μF capacitor, C_{OUT} , should be placed between the VOUT and GND pins.

Physical Dimensions







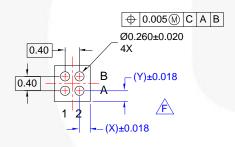
RECOMMENDED LAND PATTERN (NSMD PAD TYPE)



SIDE VIEWS

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E.PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461-539 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILNAME: MKT-UC004AFrev1.



BOTTOM VIEW

Figure 22. 4-Ball, WLCSP, 2 X 2 Array, 0.4 mm Pitch, 250 µm Ball

Product-Specific Dimensions

Product	D	E	X	Υ
FDZ8040L	0.8 ±0.03 mm	0.8 ±0.03 mm	0.21 mm	0.21 mm

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Definition of Terms

Definition of Terms				
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